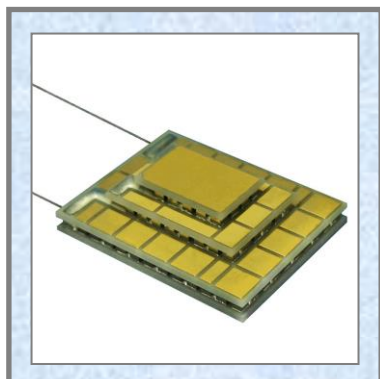


# THERMO MODULE DATA

**Model** K3MC011

RoHS 2002/95/EC Compliant

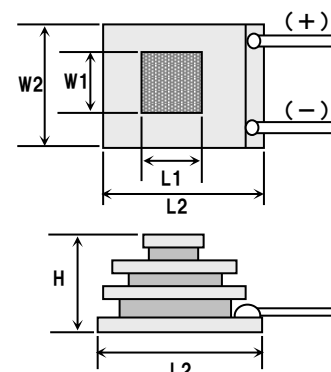
Two-stage Module



Th	$\Delta T_{max}(^{\circ}C)$	$I_{max}(A)$	$V_{max}(v)$	$Q_{cmax}(w)$
27°C	115	5.0	7.5	6.2
50°C	130	5.0	8.5	6.8

	W1	L1	W2	L2	H
Size(mm)	8.5	13.0	21.5	28.0	7.30
Tolerance(mm)	$\pm 0.1$	$\pm 0.1$	$\pm 0.2$	$\pm 0.2$	$\pm 0.4$
Metallization	Cu-Ni-Au				
Ceramic material	Aluminum nitride				
Assembly solder	SnAgCu				



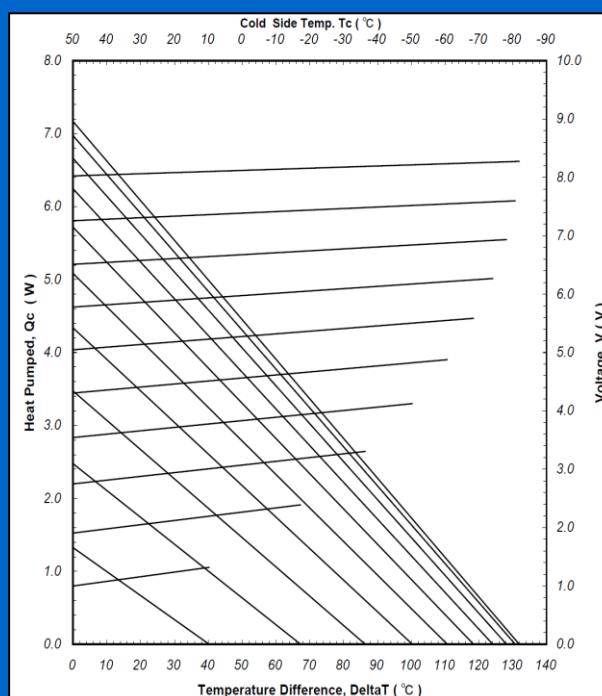
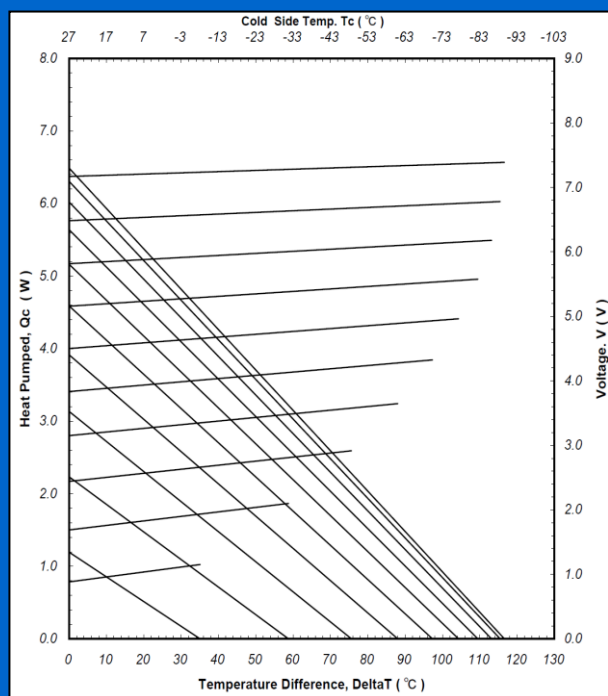
## Option

Pretinning solder InSn (melting point:117°C), BiSn (melting point:138°C)

## Performance Diagram

Th=27°C

Th=50°C



**Ambient** Vacuum

**Current value** I = 0.6 - 5.1 A ( Step = 0.5 A )

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